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ABSTRACT

METHOD FOR POSITIONING CHIPS DURING THE PRODUCTION OF A RECONSTITUTED WAFER

The invention relates to a method for fabricating a re-built wafer (100) which comprises chips (1) having connection pads (10), this method comprising the following steps of:

- fabricating a first wafer of chips (1).

It also comprises the following steps:

- production on this wafer of a stack of at least one layer of redistribution of the pads (10) of the chips on conductive tracks (12) designed for the interconnection of the chips, this stack being designated the main RDL layer (14),
- cutting this wafer in order to obtain individual chips (1) each furnished with their RDL layer (14),
- transferring the individual chips with their RDL layer (14) to a sufficiently rigid support (20) to remain flat during the following steps, which support is furnished with an adhesive layer (21), with the RDL layer (14) on the adhesive layer (21),
- depositing a resin (30) in order to encapsulate the chips (1),
- polymerizing the resin,
- removing the rigid support (20),
- depositing a single redistribution layer called a mini RDL (24) in order to connect the conductive tracks of the main RDL layer (14) up to interconnection contacts, through apertures (22) made in the adhesive layer (21), the wafer comprising the polymerized resin, the chips with their RDL layer and the mini RDL being the re-built wafer (100).

No FIGURE

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